

RoHS Compliant Product  
A suffix of "-C" specifies halogen & lead-free

## DESCRIPTION

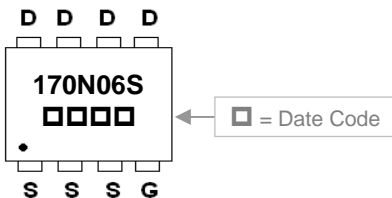
The SPR170N06S-C is the Shielded Gate Technology N-ch MOSFETs with extreme high cell density, which provide excellent  $R_{DS(ON)}$  and gate charge for most of the synchronous buck converter applications.

The SPR170N06S-C meet the RoHS and Green Product requirement with full function reliability approved.

## FEATURES

- Shielded Gate Trench Technology
- Super Low Gate Charge
- Green Device Available

## MARKING

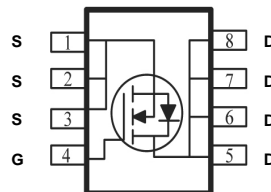


## PACKAGE INFORMATION

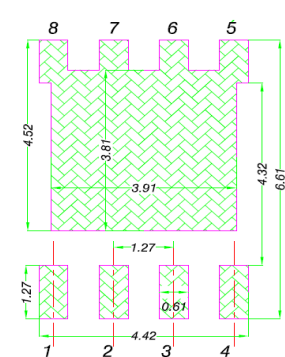
Package	MPQ	Leader Size
PR-8PP	3K	13 inch

## ORDER INFORMATION

Part Number	Type
SPR170N06S-C	Lead (Pb)-free and Halogen-free



### Mounting Pad Layout



\*Dimensions in millimeters

## ABSOLUTE MAXIMUM RATINGS ( $T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup> (Silicon Limited)	$I_D$	$T_C=25^\circ\text{C}$	170
		$T_C=100^\circ\text{C}$	107
Continuous Drain Current <sup>1 5</sup> (Package Limited)	$I_D$	$T_C=25^\circ\text{C}$	100
		$T_C=100^\circ\text{C}$	100
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	400	A
Power Dissipation <sup>3</sup>	$P_D$	83	W
Operating Junction & Storage Temperature Range	$T_J, T_{STG}$	-55~150	$^\circ\text{C}$
Thermal Resistance Ratings			
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	55	$^\circ\text{C/W}$
Thermal Resistance Junction-Case <sup>1</sup>	$R_{\theta JC}$	1.1	

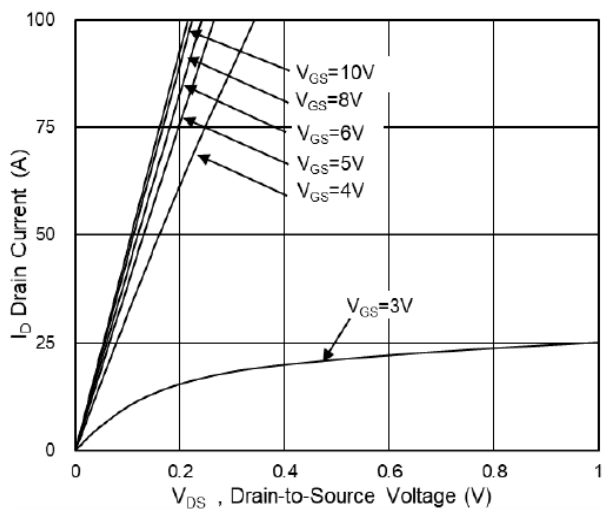
**ELECTRICAL CHARACTERISTICS** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions	
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	60	-	-	V	$V_{GS}=0V, I_D=250\mu A$	
Gate-Threshold Voltage	$V_{GS(th)}$	1	-	2.5	V	$V_{DS}=V_{GS}, I_D=250\mu A$	
Transconductance	$g_{fs}$	-	60	-	S	$V_{DS}=5V, I_D=20A$	
Gate-Source Leakage Current	$I_{GSS}$	-	-	$\pm 100$	nA	$V_{GS}=\pm 20V, V_{DS}=0V$	
Drain-Source Leakage Current	$I_{DSS}$	$T_J=25^\circ\text{C}$	-	-	1	uA	$V_{DS}=52V, V_{GS}=0V$
		$T_J=55^\circ\text{C}$	-	-	5		
Static Drain-Source On-Resistance <sup>2</sup>	$R_{DS(ON)}$	-	1.7	2.1	m $\Omega$	$V_{GS}=10V, I_D=20A$	
		-	2.3	3.2		$V_{GS}=4.5V, I_D=20A$	
Gate Resistance	$R_g$	-	1.6	-	$\Omega$	$f=1\text{MHz}$	
Total Gate Charge (4.5V)	$Q_g$	-	54.1	-	nC	$I_D=20A$ $V_{DS}=30V$ $V_{GS}=10V$	
Total Gate Charge		-	102	-			
Gate-Source Charge		-	15.7	-			
Gate-Drain Charge		-	27.9	-			
Turn-on Delay Time	$T_{d(on)}$	-	15	-	nS	$V_{DD}=30V$ $I_D=20A$ $V_{GS}=10V$ $R_G=3\Omega$	
Rise Time	$T_r$	-	12	-			
Turn-off Delay Time	$T_{d(off)}$	-	60	-			
Fall Time	$T_f$	-	19	-			
Input Capacitance	$C_{iss}$	-	5471	-	pF	$V_{GS}=0V$ $V_{DS}=30V$ $f=1\text{MHz}$	
Output Capacitance	$C_{oss}$	-	1847	-			
Reverse Transfer Capacitance	$C_{rss}$	-	86	-			
<b>Source-Drain Diode</b>							
Diode Forward Voltage <sup>2</sup>	$V_{SD}$	-	-	1.2	V	$I_S=1A, V_{GS}=0V, T_J=25^\circ\text{C}$	
Continuous Source Current <sup>1,4</sup>	$I_S$	-	-	170	A	$V_G=V_D=0V, \text{Force Current}$	
Reverse Recovery Time	$t_{rr}$	-	50	-	nS	$I_F=20A, di/dt=100A/\mu s,$ $T_J=25^\circ\text{C}$	
Reverse Recovery Charge	$Q_{rr}$	-	72	-	nC		

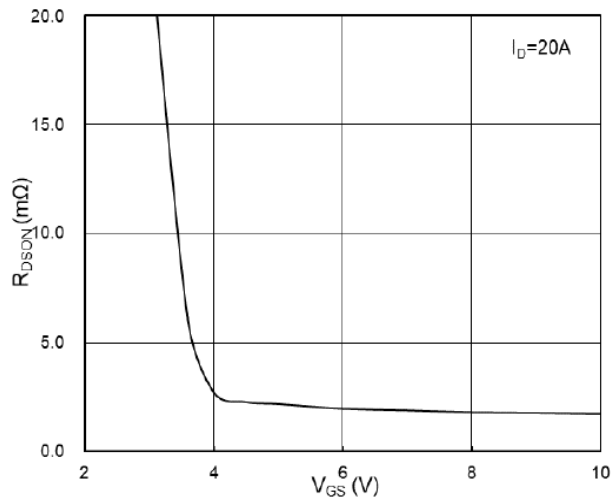
Notes:

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2oz copper.
2. The data tested by pulsed, pulse width $\leq 300\mu s$ , duty cycle $\leq 2\%$ .
3. The power dissipation is limited by 150 $^\circ\text{C}$  junction temperature.
4. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.
5. The maximum current rating is package limited.

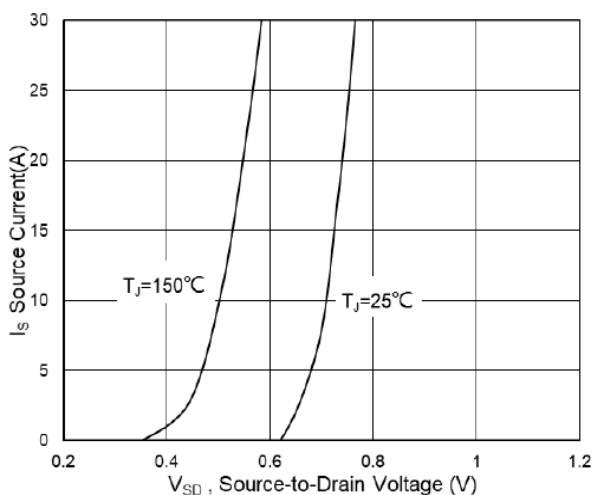
**CHARACTERISTIC CURVES**



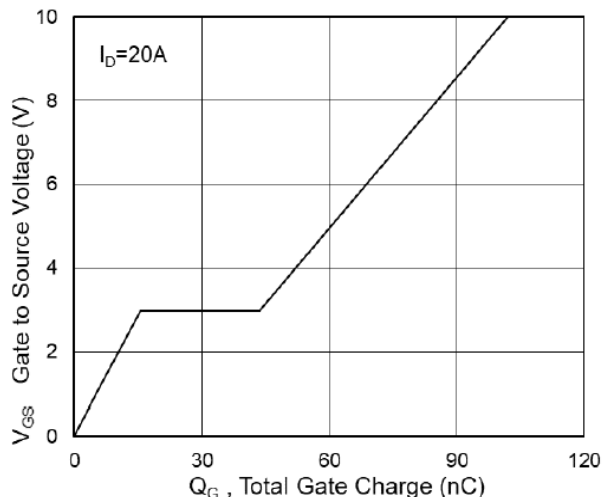
**Fig.1 Typical Output Characteristics**



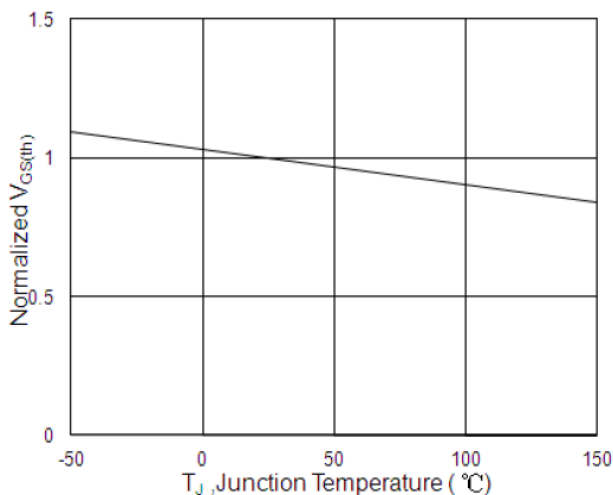
**Fig.2 On-Resistance vs G-S Voltage**



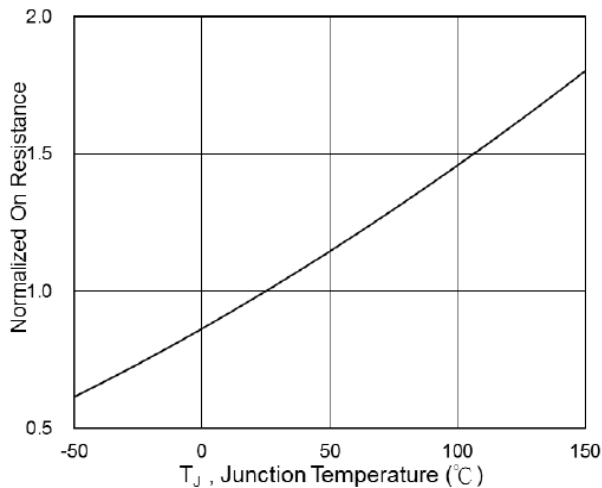
**Fig.3 Diode Forward Voltage vs Current**



**Fig.4 Gate-Charge Characteristics**

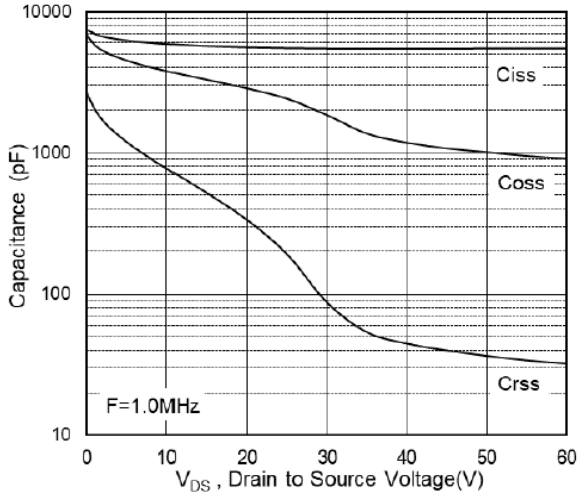


**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**

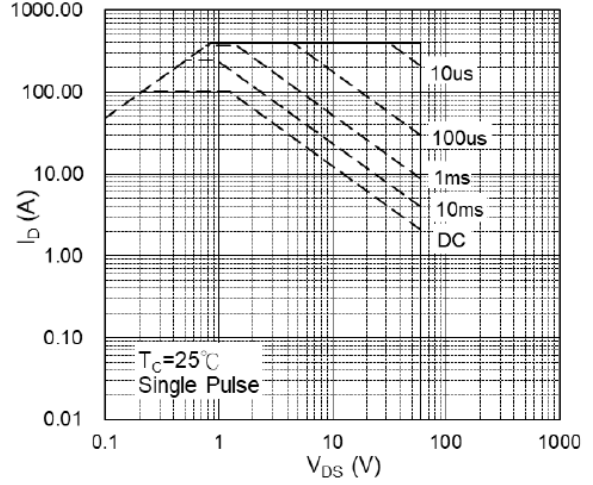


**Fig.6 Normalized  $R_{DS(ON)}$  vs  $T_J$**

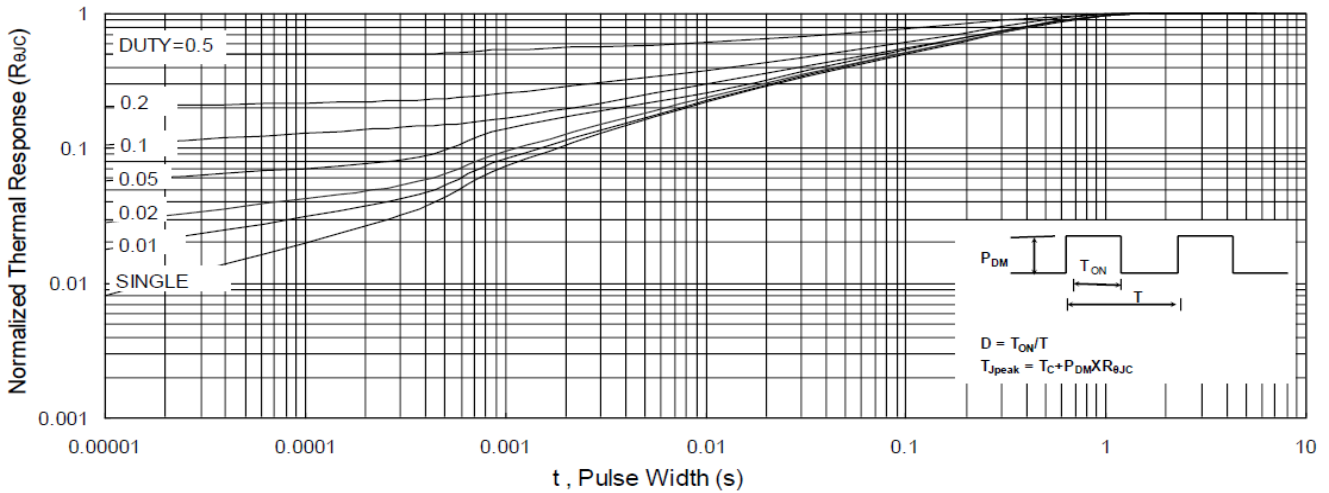
**CHARACTERISTIC CURVES**



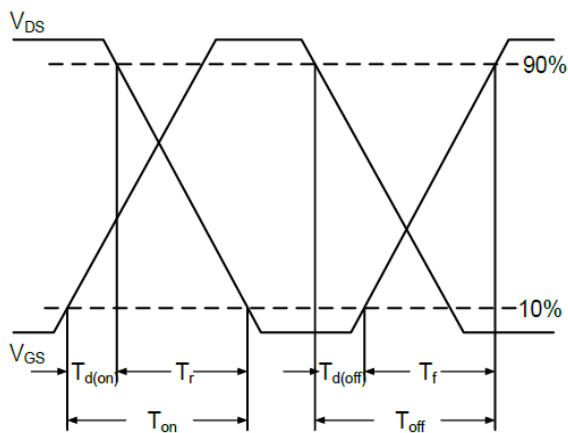
**Fig.7 Capacitance**



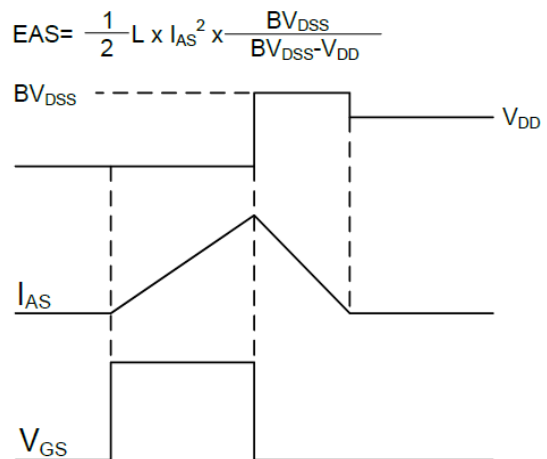
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**